



SOD882D

plastic, leadless ultra small plastic package; 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.4 mm body

5 June 2020

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	DFN1006D-2
Package type industry code	DFN1006D-2
Package style descriptive code	SOD (small outline diode)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-09-2010
Manufacturer package code	SOD882

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.55	0.6	0.65	mm
package width	0.95	1	1.05	mm
seated height	-	0.37	0.4	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	2	-	



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2 Package outline

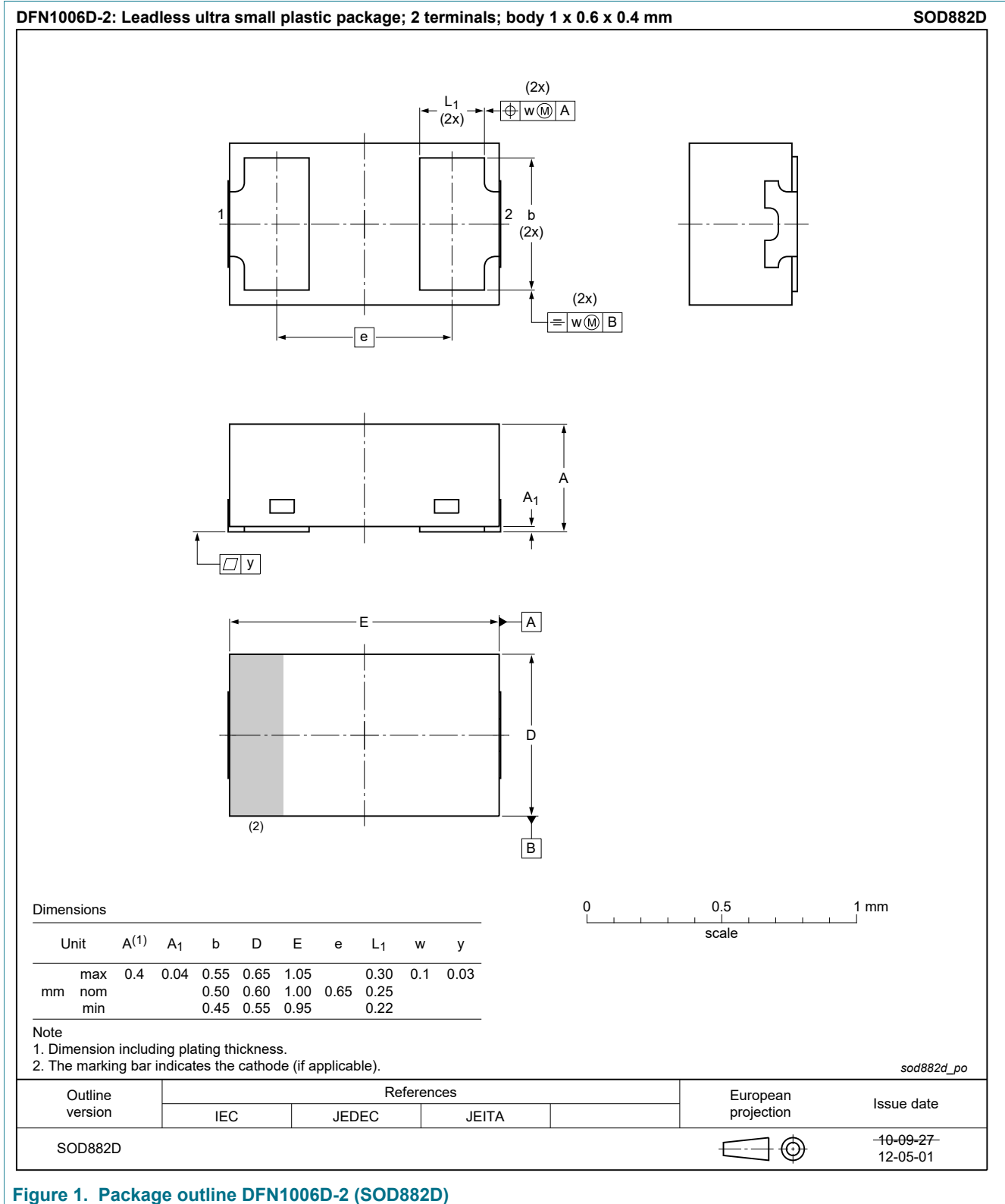


Figure 1. Package outline DFN1006D-2 (SOD882D)

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3 Soldering

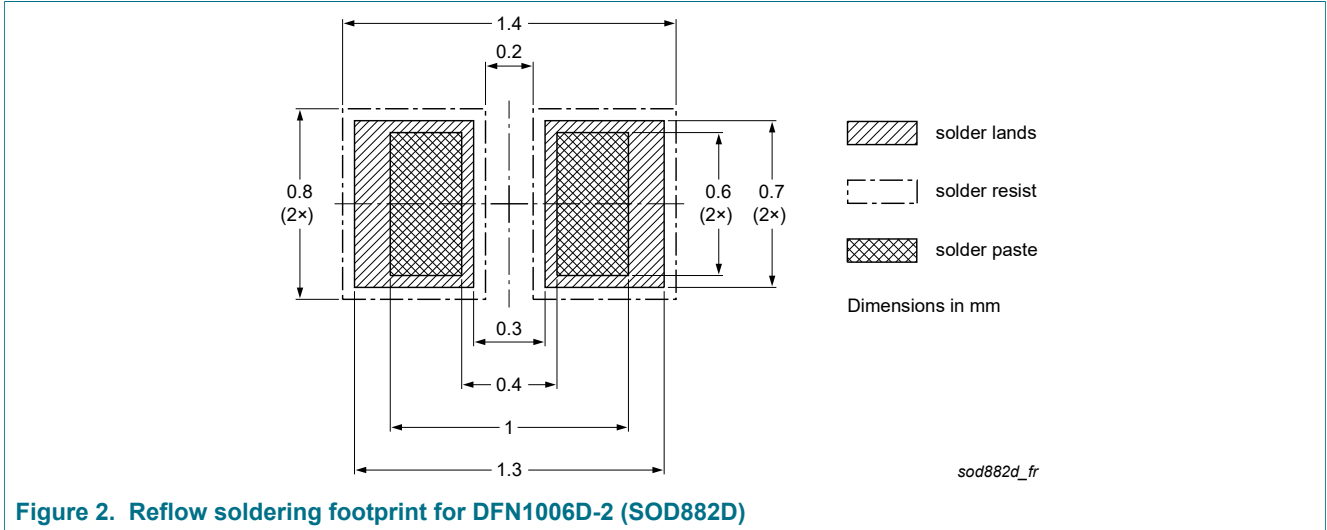


Figure 2. Reflow soldering footprint for DFN1006D-2 (SOD882D)

4 Legal information

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